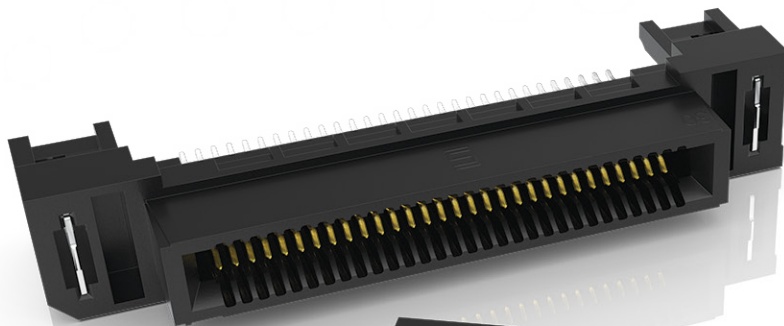


GENERATE[®]

HIGH-SPEED EDGE CARD SYSTEMS

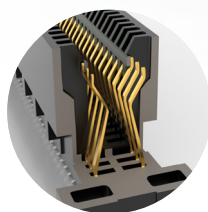
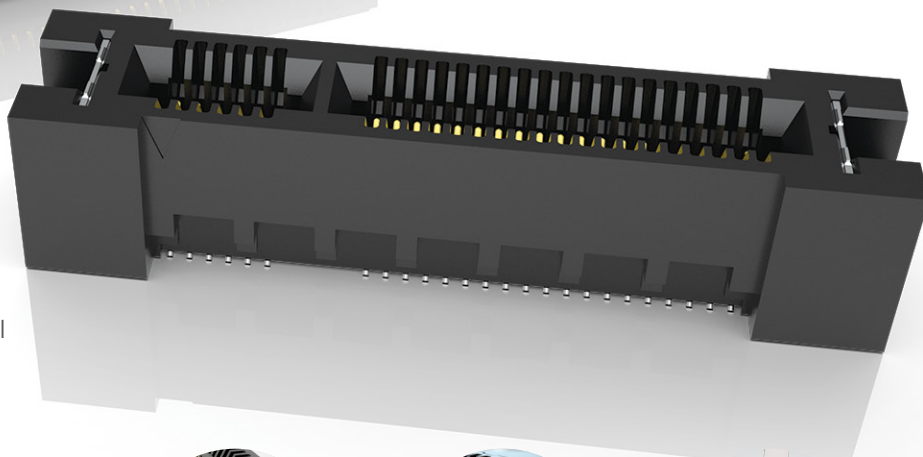
0.60 mm, 0.80 mm and 1.00 mm PITCH



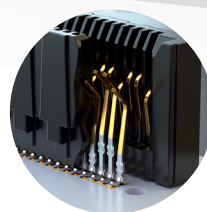
**EDGE
RATE[®]**
CONTACT

FEATURES & BENEFITS

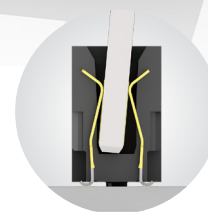
- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express[®] 3.0, 4.0, 5.0 and 6.0
- Edge Rate[®] contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available



Rugged tucked beam technology (HTEC8)



Differential pair for increased speed (HSEC8-DP)



Custom designs allow for misalignment in the X-Y axes (HSEC1)

The PCI Express[®] design marks are registered trademarks and/or service marks of PCI-SIG.

KEY SPECIFICATIONS

SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC/339 VDC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DV	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-RA	0.80 mm	18-120	Black LCP	BeCu	-55 °C to +125 °C	2.6 A (2 pins)	175 VAC/247 VDC	Yes
HSEC8-EM	0.80 mm	20-120	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PE	0.80 mm	20-40	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PV	0.80 mm	40-80	Black LCP	BeCu	-55 °C to +125 °C	3.2 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DP	0.80 mm	16-112	Black LCP	BeCu	-55 °C to +125 °C	2.7 A (2 pins)	235 VAC/332 VDC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC/304 VDC	Yes

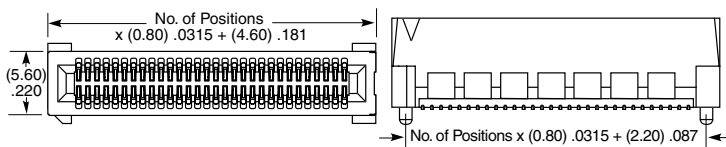
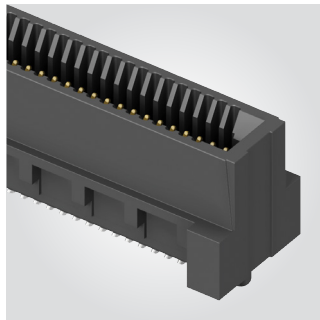
(0.80 mm) .0315" PITCH • VERTICAL EDGE CARD SOCKET

HSEC8	1	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	DV	A	OTHER OPTIONS	"X"R
		09, 10, 13, 20, 25, 30, 37, 40, 49, 50, 60, 70, 80, 100 (13, 25, 49 only available with -L or -L2 latching option; 09 only available with -L2 option; 37 only available with -L latching option)	-01 = (1.60 mm) .062" thick card -03 = (2.36 mm) .093" thick card	-L = 10 μm (0.25 μm) Gold on contact area, Matte Tin on tail -S = 30 μm (0.76 μm) Gold on contact area, Matte Tin on tail			-K = Polyimide Pick & Place Pad -BL = Board Locks; -01 card only (Weld tab standard) -L = Latching Option; -01 card only (13, 25, 37, 49 only) (Weld tab standard) -L2 = ECDP Latching; -01 card only (09, 13, 25, 49 only) (For use with ECDP) (Weld tab standard) -WT = Weld tab	Leave blank for Tray Packaging -TR = Tape & Reel (09 - 70 only) -FR = Full Reel Tape & Reel (must order max. quantities per reel; contact Samtec for quantity breaks) (09-70 only)

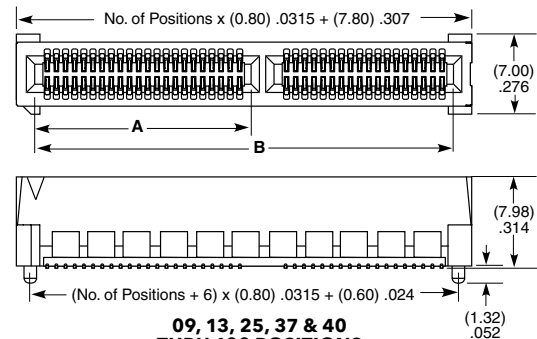
HSEC8-DV

Card Mates:
 (1.60 mm) .062" card,
 (2.36 mm) .093" card,
 HSC8

Cable Mates:
 ECDP



10, 20, & 30 POSITIONS



09, 13, 25, 37 & 40 THRU 100 POSITIONS

OTHER SOLUTIONS

For complete edge card system with cards and sockets, visit samtec.com?RU8

For a card to mate with an HSEC8 socket, visit samtec.com?HSC8



POSITIONS PER ROW	A	B	CABLE	CONNECTOR
09*†	(4.50) .177	(11.80) .465	ECDP-04	HSEC8-109-L2
13*†	(6.10) .240	(15.00) .591	ECDP-08	HSEC8-113-L2
25*†	(6.10) .240	(24.60) .969	ECDP-16	HSEC8-125-L2
37†	(18.10) .713	(34.20) 1.346	ECDP-32	HSEC8-149-L2
40	(18.90) .744	(36.60) 1.441		
49*†	(22.90) .902	(43.80) 1.724		
50	(22.90) .902	(44.60) 1.756		
60	(26.90) 1.059	(52.60) 2.071		
70†	(26.90) 1.059	(60.60) 2.386		
80†	(26.90) 1.059	(68.60) 2.701		
100†	(26.90) 1.059	(84.60) 3.331		

Positions where no dimensions are given do not have keying feature.

* Mates with ECDP Series

† Available with -01 Card Only

Note:
 Some sizes, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?HSEC8-DV